

FROM RAM TOP SURFACE TO SMT SURFACE

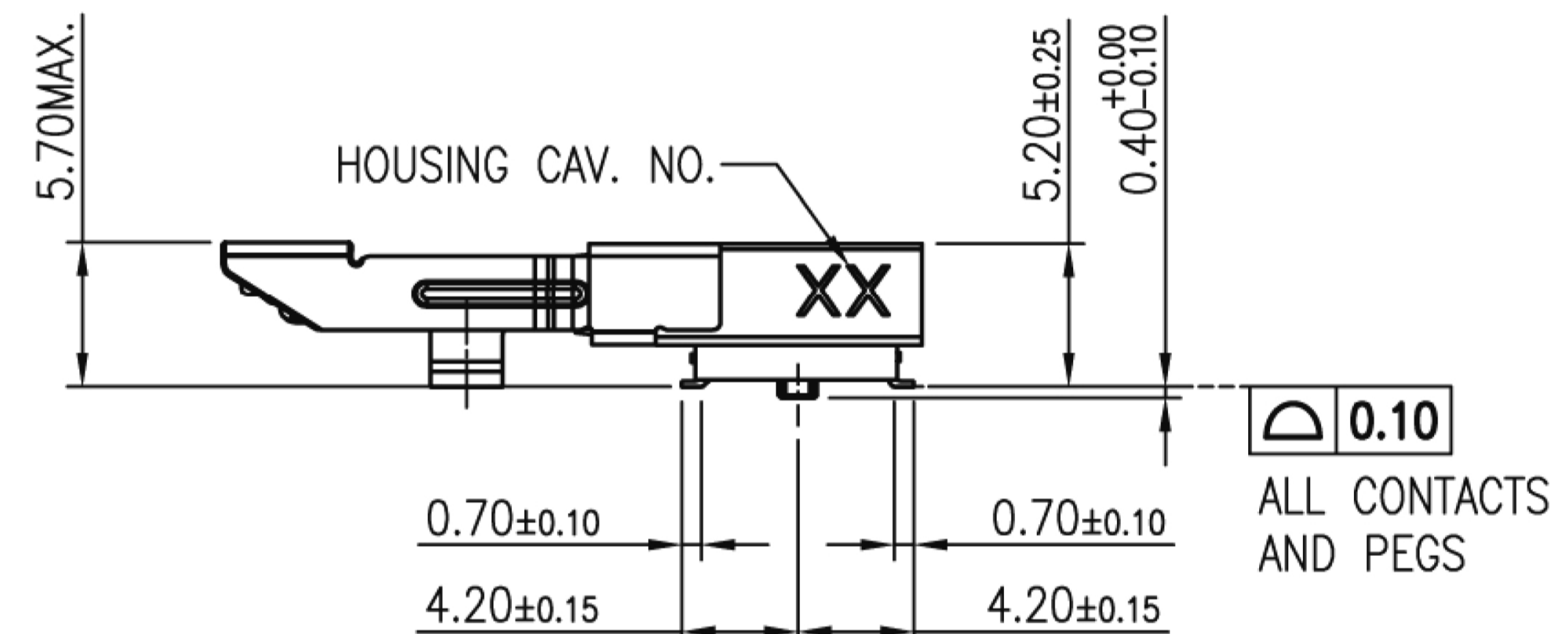
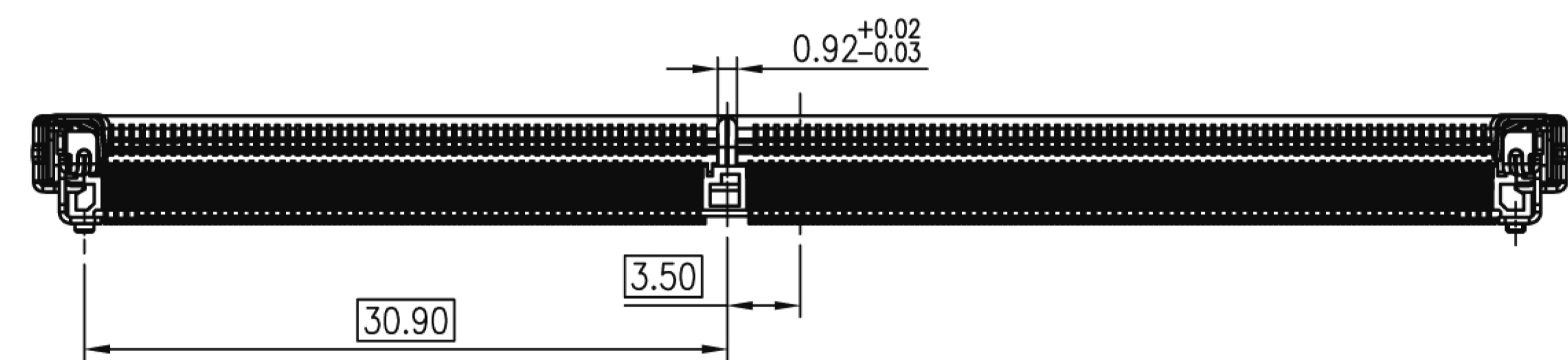
FROM RAM BOTTOM SURFACE TO SMT SURFACE

MATING: ① INSERTING → ② ROTATING → ③ FIXED

UNMATING: ④ UNFIXED → ⑤ ROTATING → ⑥ WITHDRAWING

MATING/UNMATING VIEW

SCALE 2:1



- NOTES
- MATERIAL
HOUSING: THERMOPLASTIC. UL94V-0.
CONTACT: HIGH-PERFORMANCE COPPER ALLOY.
LATCH: STAINLESS STEEL.
PEG: STAINLESS STEEL.
 - FINISH
CONTACT: GOLD PLATING(SEE NOTE 4) ON CONTACT AREA AND 1u"~3u"GOLD PLATING ON SOLDER AREA
NICKEL(SEE TABLE 1) UNDER PLATING OVER ALL
PEG: 50u"~150u" TIN PLATING OVER ALL
50u"~150u" NICKEL UNDER PLATING OVER ALL
 - MSL LEVEL:
MSL(MOISTURE SENSIVITY LEVEL)=1.

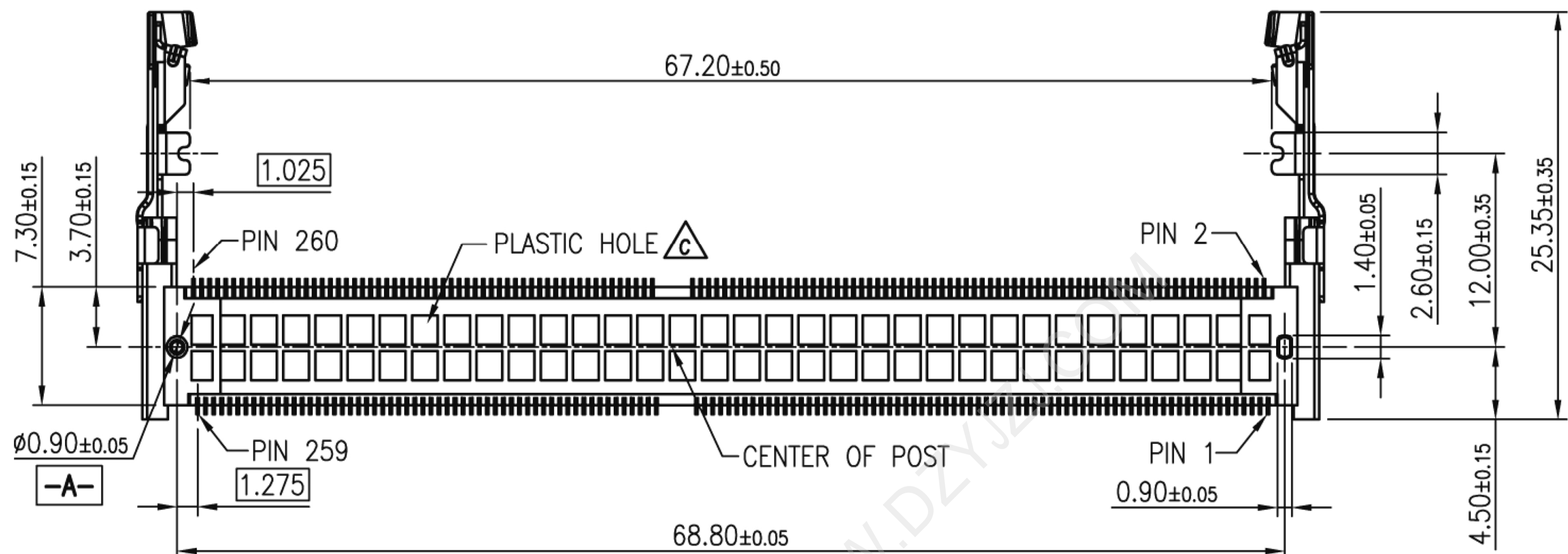


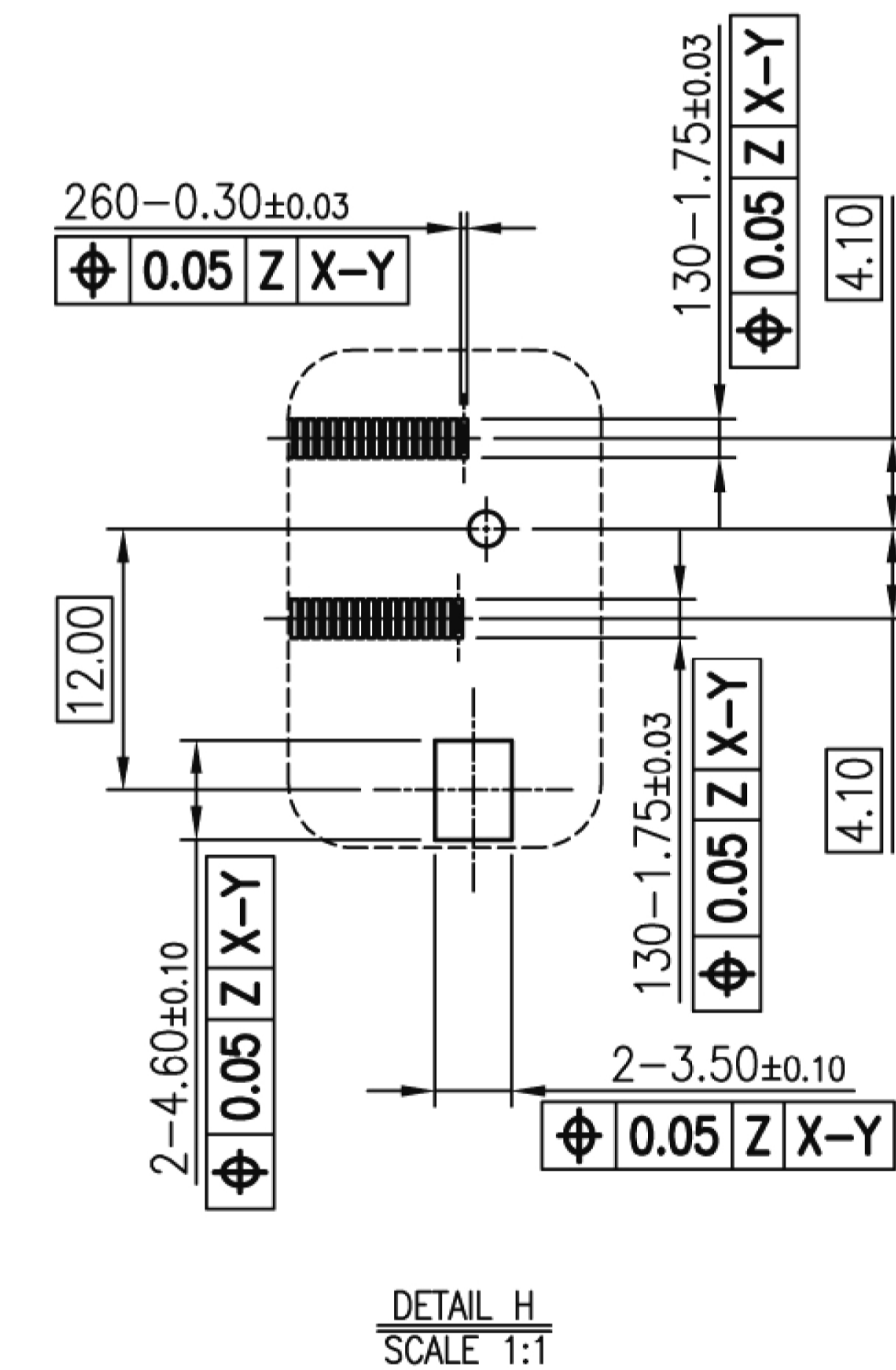
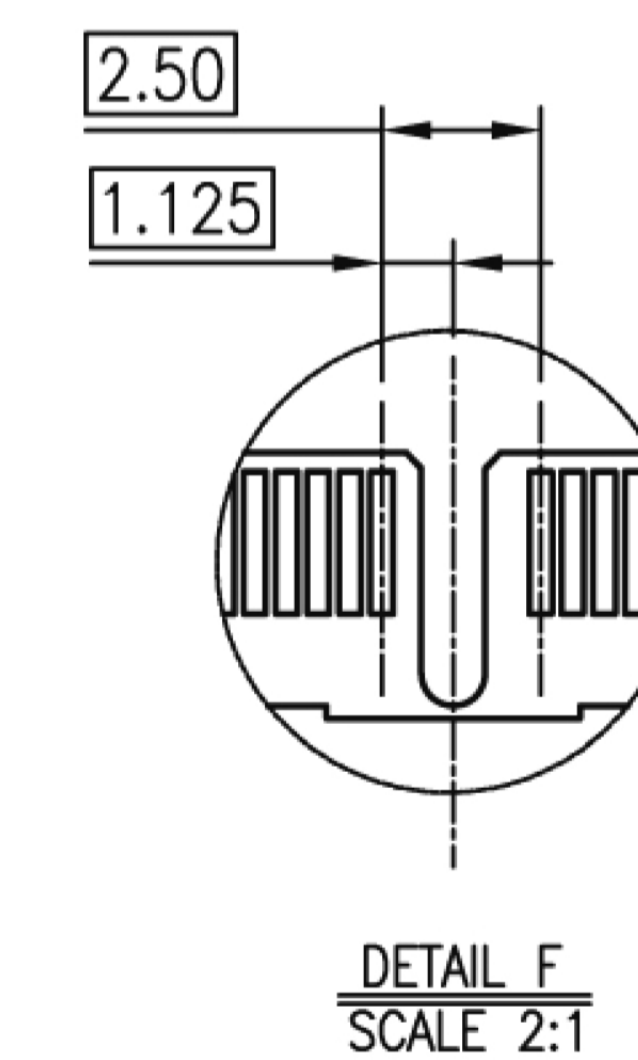
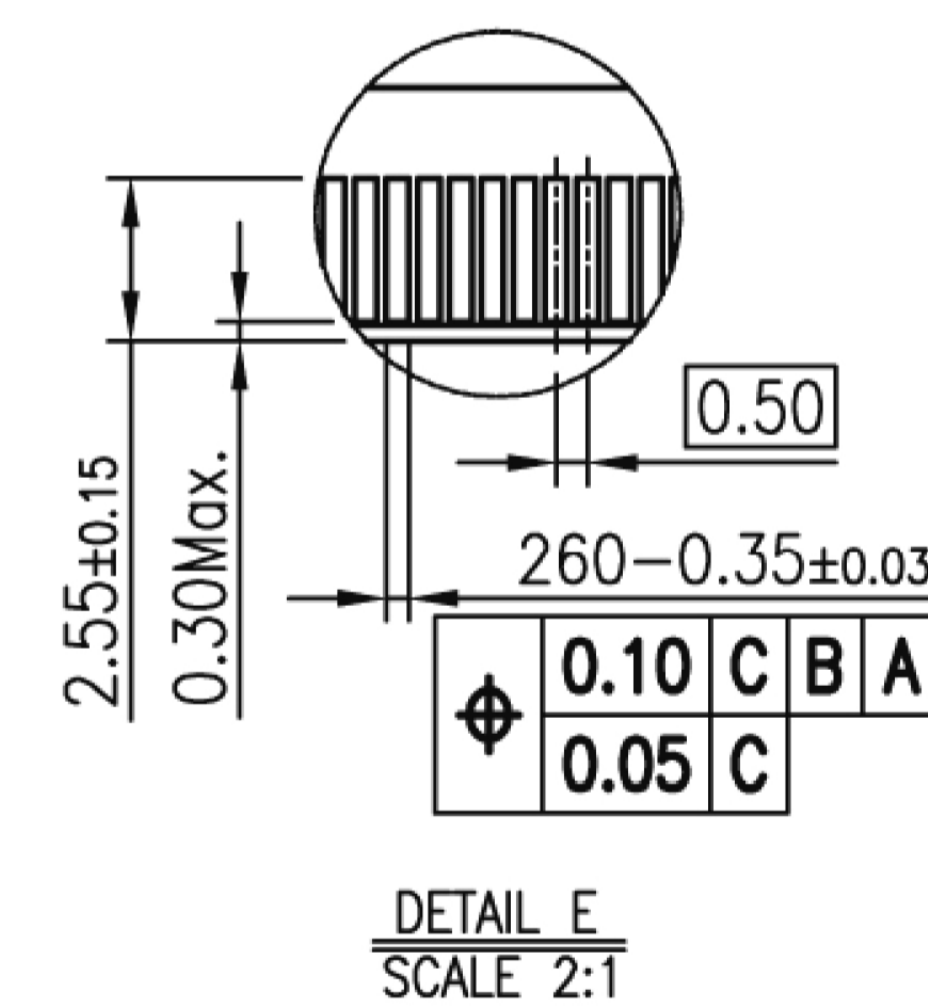
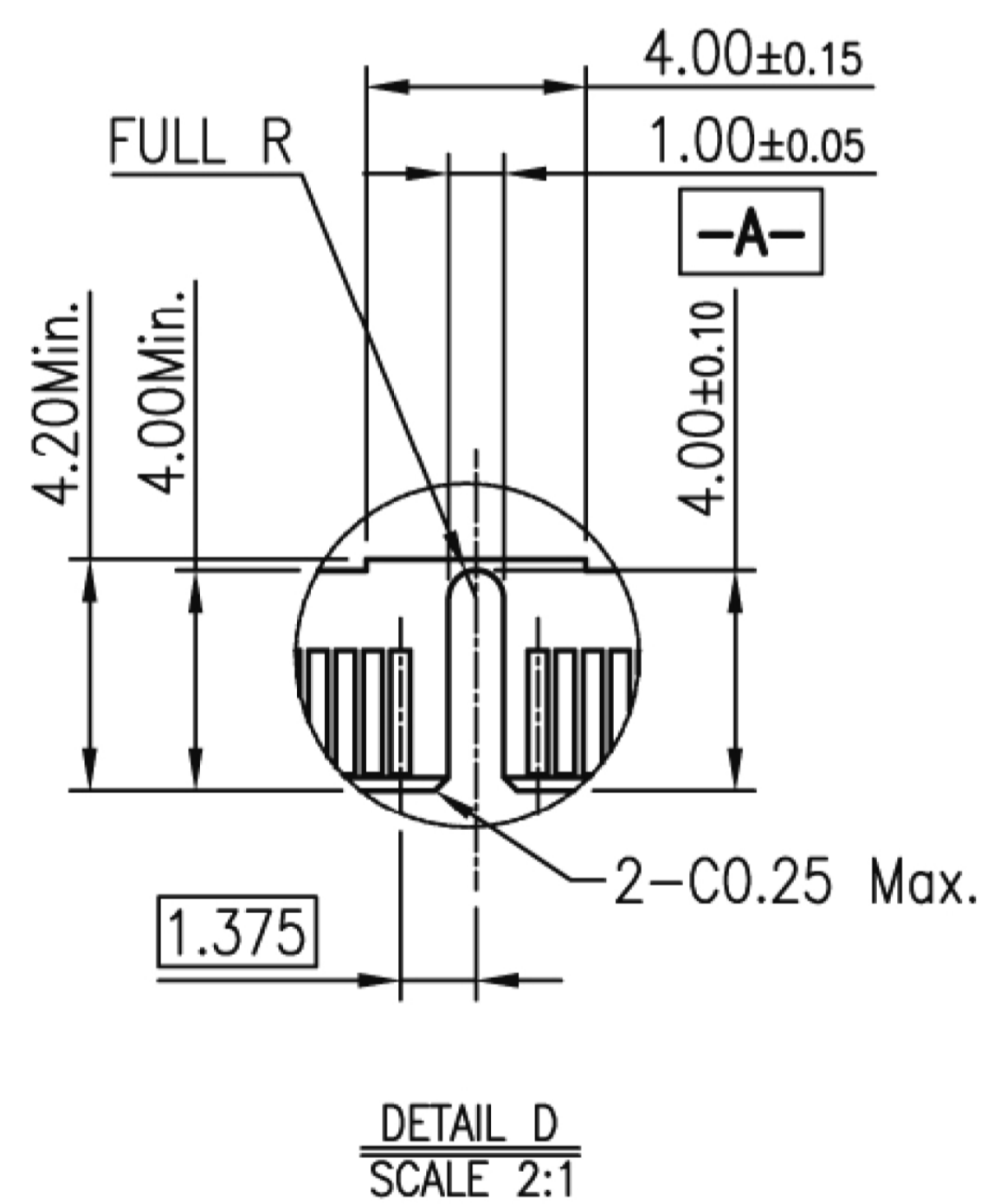
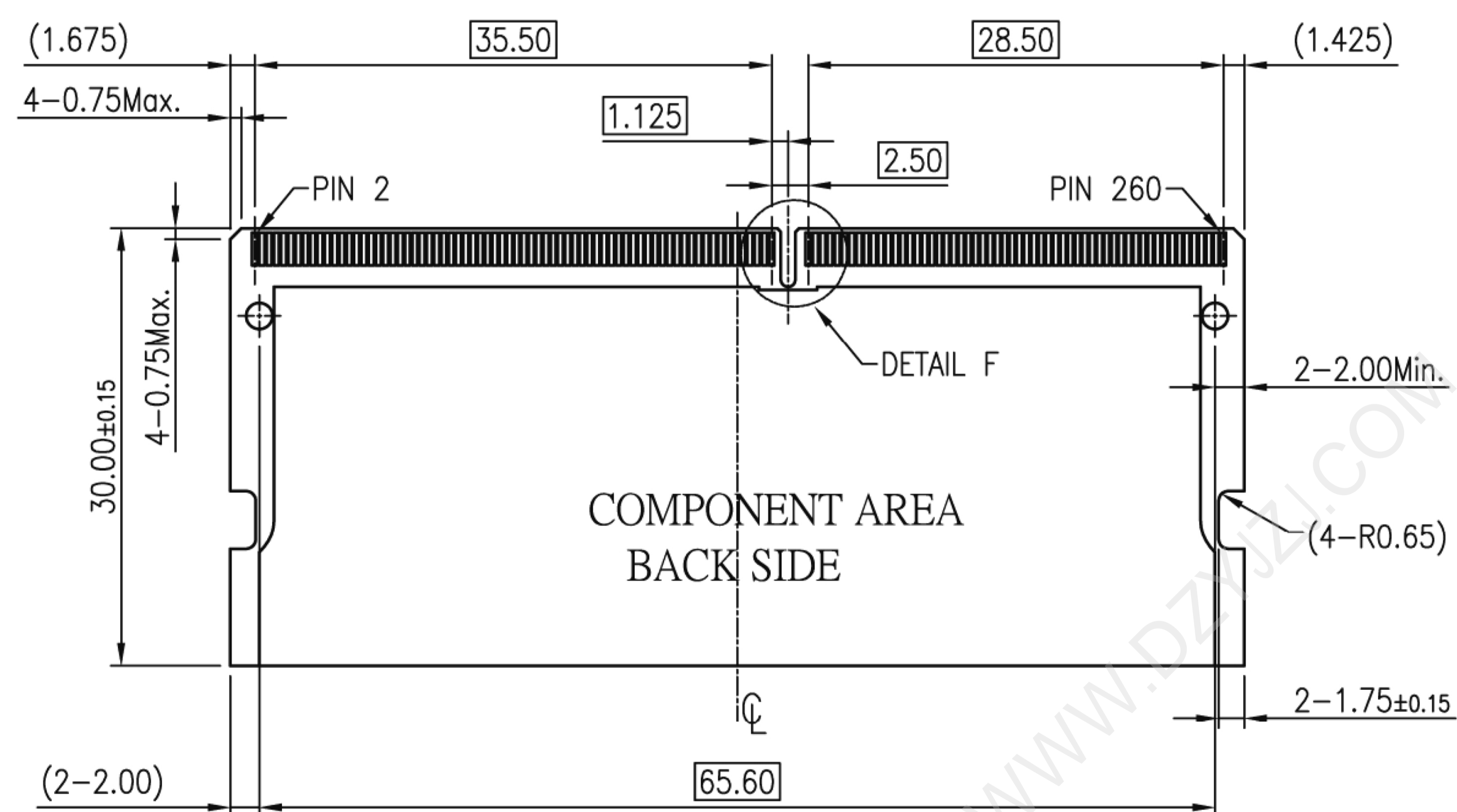
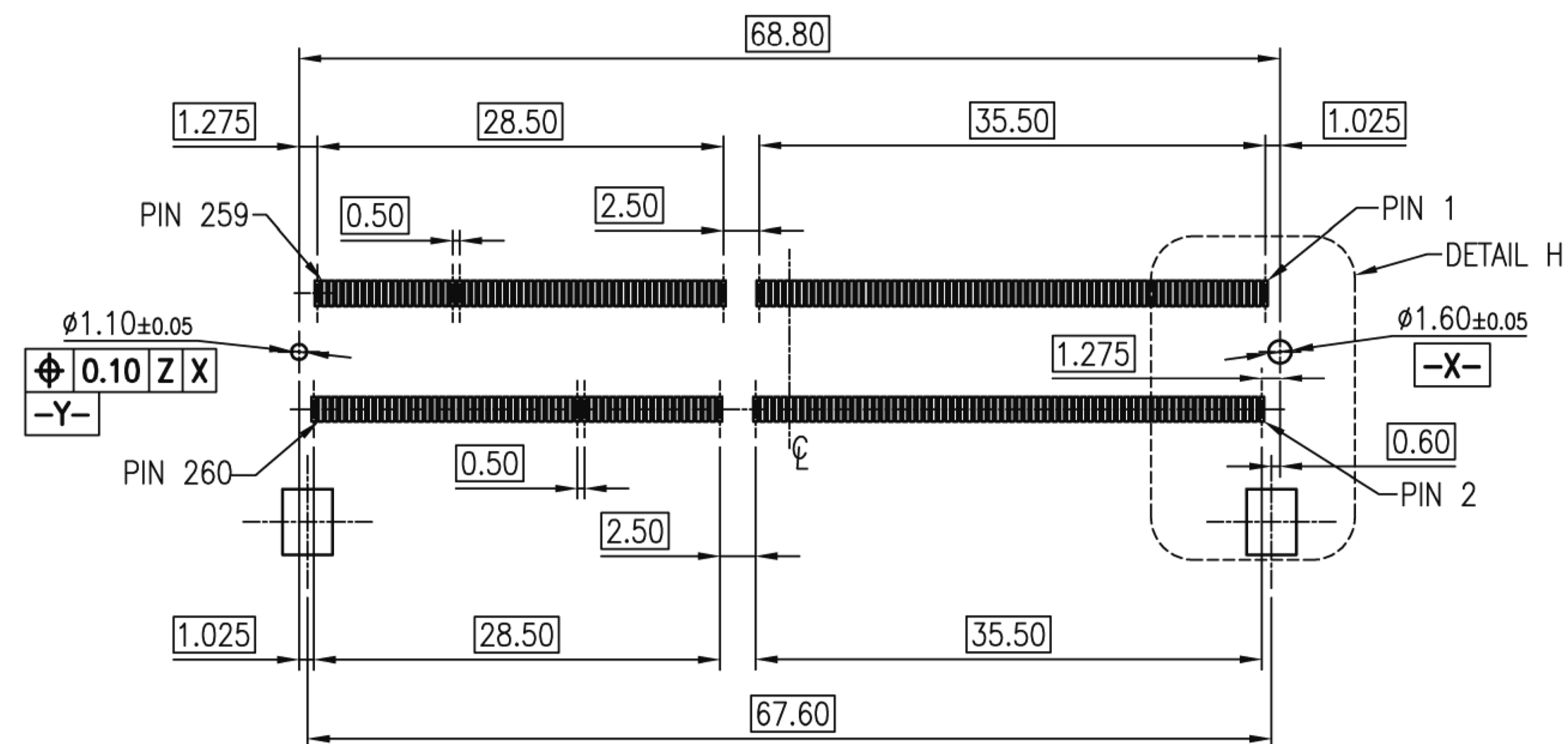
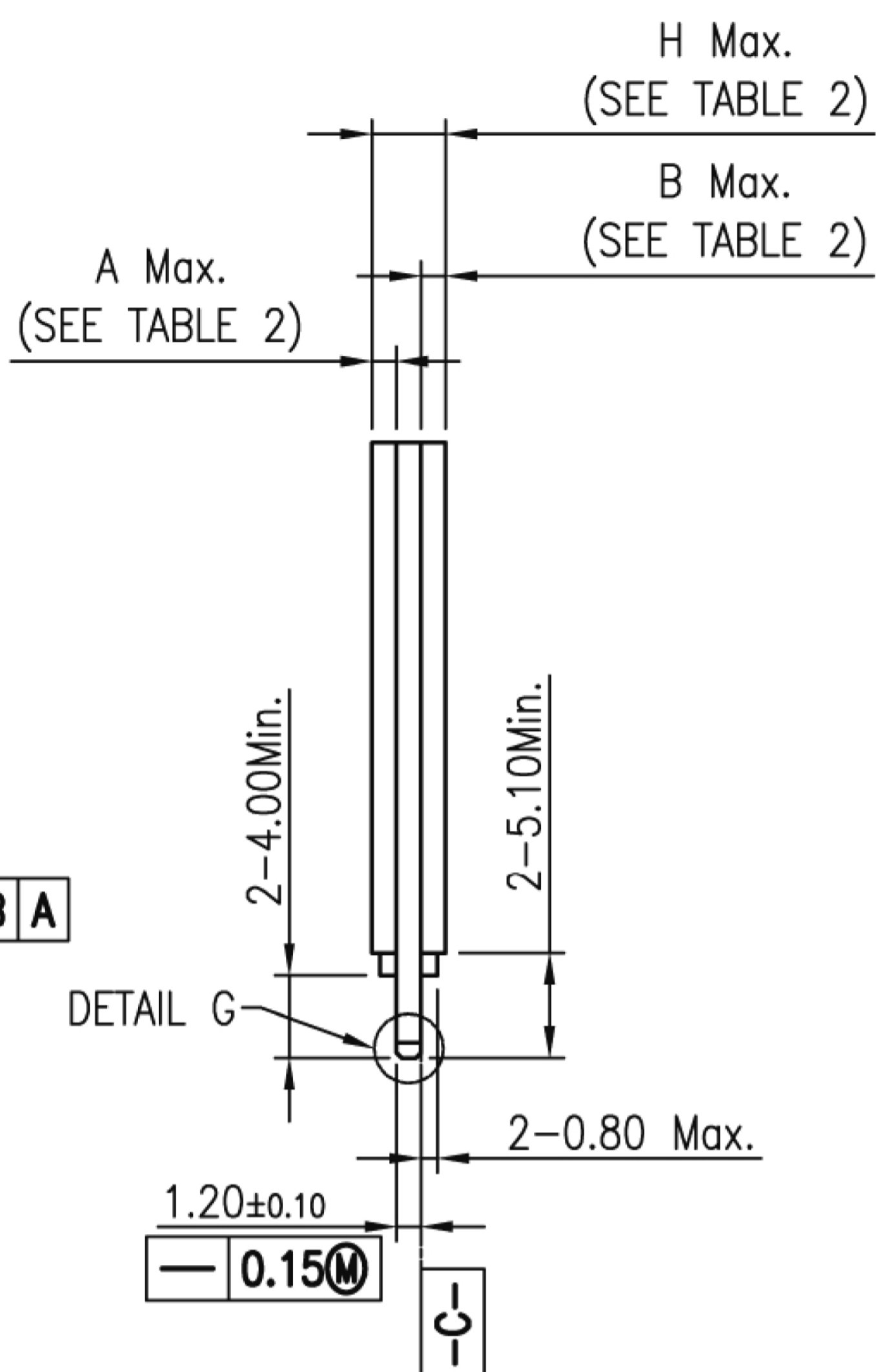
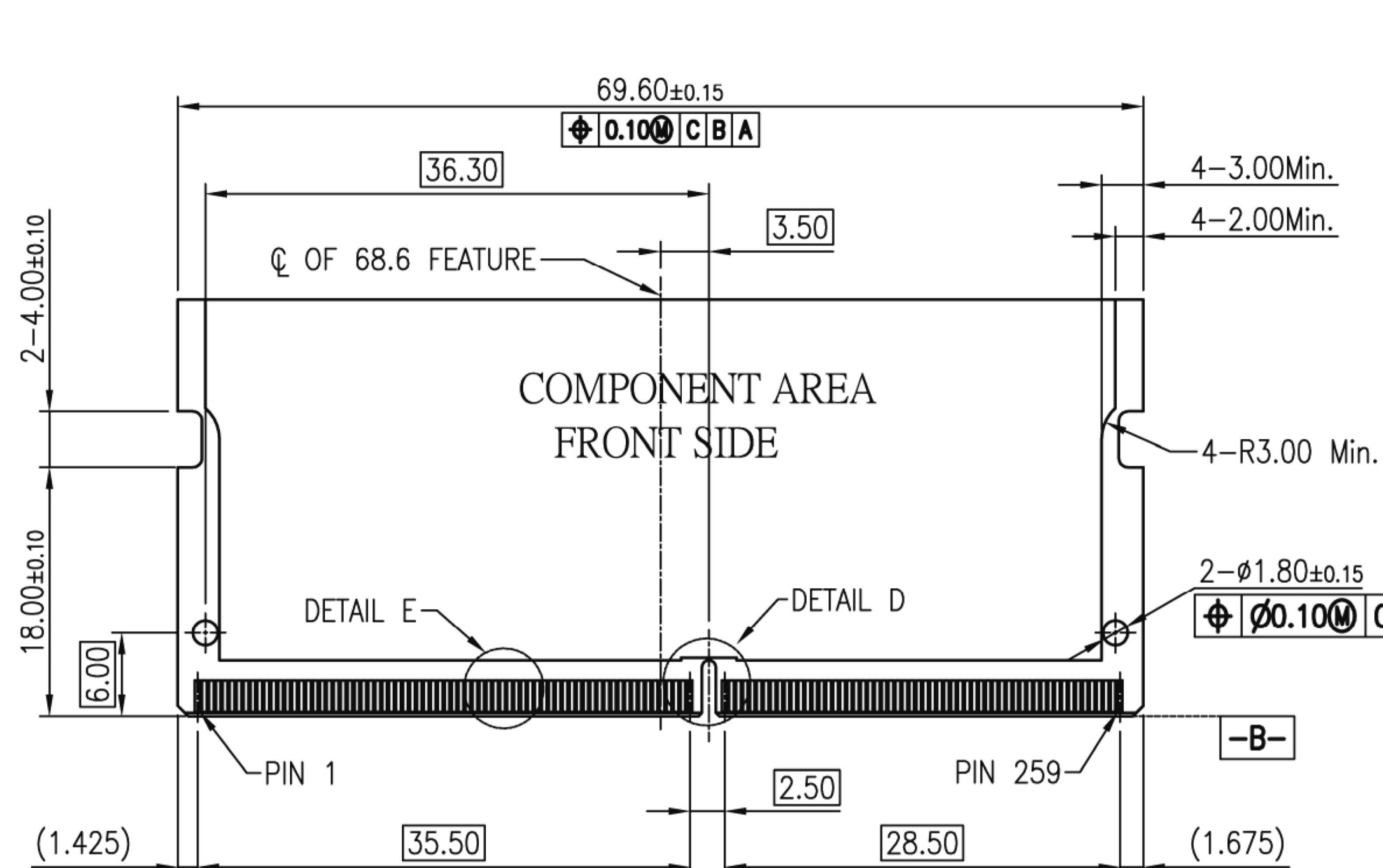
TABLE1:

| TRADEMARK | CONTACT NICKEL FINISH | CONTACT AREA PLATING SPEC | HOUSING COLOR | PACKING |
|------------|-----------------------|---------------------------|---------------|-----------|
| WITH"®LTK" | 50u"~150u" | GOLD 15u"Min | BLACK | TAPE REEL |

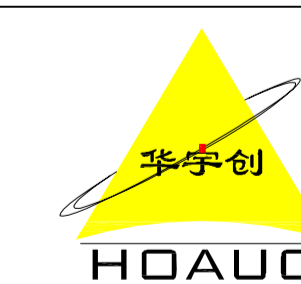
深圳市华宇创精密电子有限公司

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|--|--------------------|----------------------|--|---------------------|
| TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2" X.X* ±0.5" | DRAWN BY : 陈一鸣 | DATE : 2014-02-23 | PART NAME: SODDR4 5.2 260PIN STD TYPE | |
| UNIT: mm [inch] SCALE: 1:1 SIZE: A4 | CHECKED BY: 马跃 | DATE : 2014-02-23 | PART NO. HYC23-DDR4-520S | MOLD NO. |
| | APPROVED BY: 邱敏 | DATE : 2014-02-23 | DRAW NO. HYC-2401291819 | SHEET NO. 1 OF 1 |



RECOMMEND MODULE CONFIGURATION



深圳市华宇创精密电子有限公司

| | | | | |
|--|--------------------|----------------------|--|---------------------|
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